

PROBE CARD COOLING ASSEMBLY WITH DIRECT COOLING OF
ACTIVE ELECTRONIC COMPONENTS

ABSTRACT OF THE DISCLOSURE

A probe card cooling assembly for use in a test system includes a package with one or more dies cooled by direct cooling. The cooled package includes one or more dies with active electronic components and at least one coolant port that allows a coolant to enter the high-density package and directly cool the active electronic components of the dies during a testing operation.

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